

**Product / Package Information**

Package	LFCSP - Punched
Body Size (mm)	10 X 10 X 0.85 (8.5 EP)
Lead Count	72
Terminal Finish	100 Sn

**Environmental Information**

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

**Materials Declaration**

**Molding Compound**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	9.19E-02	86.91	869100	27.12	271221
Thermosets	Epoxy & Phenol Resin	Proprietary	1.35E-02	12.78	127800	3.99	39883
Other inorganic materials	Carbon black	1333-86-4	3.28E-04	0.31	3100	0.10	967
Subtotal			1.06E-01	100.00	1000000	31.21	312071

**Leadframe**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.76 E-01	97.50	975000	52.01	520055
Copper & its alloys	Iron	7439-89-6	4.25 E-03	2.35	23500	1.25	12535
Copper & its alloys	Zinc	7440-66-6	2.17 E-04	0.12	1200	0.06	640
Copper & its alloys	Phosphorus	7723-14-0	5.42 E-05	0.03	300	0.02	160
Subtotal			1.81 E-01	100.00	1000000	53.34	533389

**Internal Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.81 E-03	100.0	1000000	0.53	5334

**External Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	7.89 E-03	100.0	1000000	2.33	23293

**Bond Wires**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	2.34 E-03	100.0	1000000	0.69	6907

**Chip**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	3.52 E-02	100.0	1000000	10.40	104008

**Die Attach**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.74 E-03	73.54	735400	1.103	11030
Other organic materials	Epoxy resin A	TS ref# 10013	3.73 E-04	7.35	73500	0.110	1102
Others	Anhydride	TS ref# 10181	3.73 E-04	7.35	73500	0.110	1102
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	1.49 E-04	2.94	29400	0.044	441
Other organic materials	Epoxy resin B	TS ref# 10237	1.49 E-04	2.94	29400	0.044	441
Others	Epoxy resin modifier	TS ref# 10038	1.49 E-04	2.94	29400	0.044	441
Others	Anhydride	TS ref# 10180	1.49 E-04	2.94	29400	0.044	441
Subtotal			5.08 E-03	100.0	911800	1.37	14999

<b>Package Totals</b>	<b>Weight (g)</b>	<b>3.39 E-01</b>	<b>Percentage (%)</b>	<b>100</b>	<b>PPM</b>	<b>1000000</b>
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Note: The information provided in this declaration are true to the best of ADI's knowledge ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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